



Integrated
Circuit
Systems, Inc.

ICS9179B-01

Low Skew Buffers

General Description

The **ICS9179B-01** generates SDRAM clock buffers required for high speed RISC or CISC microprocessor systems such as Intel PentiumPro or Pentium II. An output enable is provided for testability.

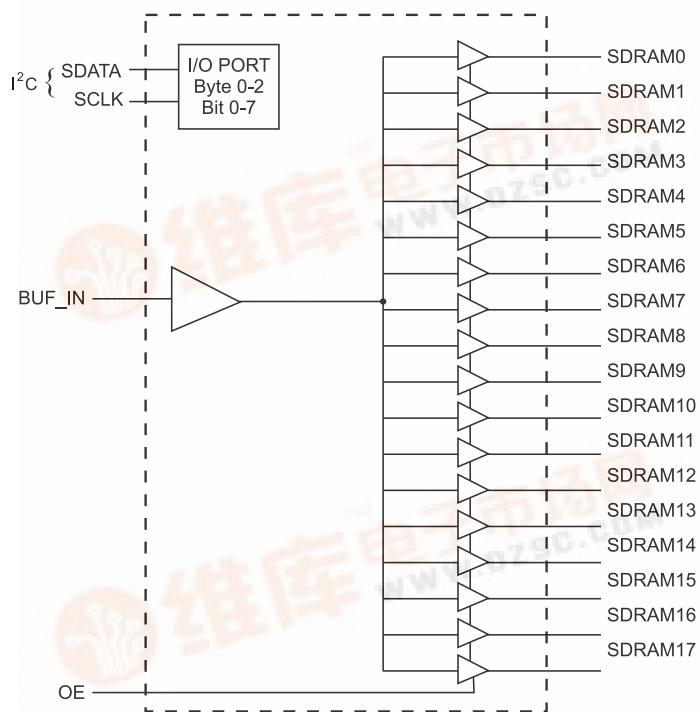
The device is a buffer with low output to output skew. This is a Fanout buffer device, not using an internal PLL. This buffer can also be a feedback to an external PLL stage for phase synchronization to a master clock.

The individual clock outputs are addressable through I²C to be enabled, or stopped in a low state for reduced EMI when the lines are not needed.

Features

- High speed, low noise non-inverting (0:17) buffer for SDRAM clock buffer applications.
- Supports up to four SDRAM DIMMS
- Synchronous clocks skew matched to 250 ps window on SDRAM.
- I²C Serial Configuration interface to allow individual clocks to be stopped.
- Multiple VDD, VSS pins for noise reduction
- Tri-state pin for testing
- Custom configurations available
- 3.0V – 3.7V supply range
- 48-pin SSOP package

Block Diagram



Pin Configuration

N/C	1	48	N/C
N/C	2	47	N/C
VDD	3	46	VDD
SDRAM0	4	45	SDRAM15
SDRAM1	5	44	SDRAM14
GND	6	43	GND
VDD	7	42	VDD
SDRAM2	8	41	SDRAM13
SDRAM3	9	40	SDRAM12
GND	10	39	GND
BUF_IN	11	38	OE
VDD	12	37	VDD
SDRAM4	13	36	SDRAM11
SDRAM5	14	35	SDRAM10
GND	15	34	GND
VDD	16	33	VDD
SDRAM6	17	32	SDRAM9
SDRAM7	18	31	SDRAM8
GND	19	30	GND
VDD	20	29	VDD
SDRAM16	21	28	SDRAM17
GND	22	27	GND
VDDS	23	26	GNDS
	24	25	I ² C { SDATA }

48-Pin SSOP



Pin Descriptions

PIN NUMBER	PIN NAME	TYPE	DESCRIPTION
4, 5, 8, 9	SDRAM (0:3)	OUT	SDRAM Byte 0 clock outputs ¹
13, 14, 17, 18	SDRAM (4:7)	OUT	SDRAM Byte 1 clock outputs ¹
31, 32, 35, 36	SDRAM (8:11)	OUT	SDRAM Byte 2 clock outputs ¹
40, 41, 44, 45	SDRAM (12:15)	OUT	SDRAM Byte 3 clock outputs ¹
21, 28	SDRAM (16:17)	OUT	SDRAM clock outputs useable for feedback. ¹
11	BUF_IN	IN	Input for buffers
38	OE	IN	Tri-states all outputs when held LOW. Has internal pull-up. ²
24	SDATA	I/O	Data pin for I ² C circuitry ³
25	SCLK	I/O	Clock pin for I ² C circuitry ³
3, 7, 12, 16, 20, 29, 33, 37, 42, 46	VDD	PWR	3.3V Power supply for SDRAM buffer
6, 10, 15, 19, 22, 27, 30, 34, 39, 43	GND	PWR	Ground for SDRAM buffer
23	VDDS	PWR	3.3V Power supply for I ² C circuitry
26	GNDS	PWR	Ground for I ² C circuitry
1, 2, 47, 48	N/C	-	Pins are not internally connected

Notes:

1. At power up all eighteen SDRAM outputs are enabled and active.
2. OE has a 100K Ohm internal pull-up resistor to keep all outputs active.
3. The SDATA and SCLK inputs both also have internal pull-up resistors with values above 100K Ohms as well for complete platform flexibility.

Power Groups

VDD = Power supply for SDRAM buffer
VDDS = Power supply for I²C circuitry

Ground Groups

GND = Ground for SDRAM buffer
GNDS = Ground for I²C circuitry



Technical Pin Function Descriptions

VDD

This is the power supply to the internal core logic of the device as well as the clock output buffers for SDRAM(0:17).

This pin operates at 3.3V volts. Clocks from the listed buffers that it supplies will have a voltage swing from Ground to this level. For the actual guaranteed high and low voltage levels for the Clocks, please consult the DC parameter table in this data sheet.

GND

This is the power supply ground (common or negative) return pin for the internal core logic and all the output buffers.

SDRAM(0:17)

These Output Clocks are use to drive Dynamic RAM's and are low skew copies of the CPU Clocks. The voltage swing of the SDRAM's output is controlled by the supply voltage that is applied to VDD of the device, operates at 3.3 volts.

I²C

The SDATA and SCLOCK Inputs are use to program the device. The clock generator is a slave-receiver device in the I²C protocol. It will allow read-back of the registers. See configuration map for register functions. The I²C specification in Philips I²C Peripherals Data Handbook (1996) should be followed.

BUF_IN

Input for Fanout buffers (SDRAM 0:17).

OE

OE tristates all outputs when held low.

VDDS

This is the power supply to I²C circuitry.

GNDS

This is the ground to I²C circuitry.



General I²C serial interface information

A. For the clock generator to be addressed by an I²C controller, the following address must be sent as a start sequence, with an acknowledge bit between each byte.

Clock Generator Address (7 bits)	ACK	+ 8 bits dummy command code	ACK	+ 8 bits dummy Byte count	ACK
A(6:0) & R/W#					
D2(H)					

Then Byte 0, 1, 2, etc in sequence until STOP.

B. The clock generator is a slave/receiver I²C component. It can "read back" (in Philips I²C protocol) the data stored in the latches for verification. (set R/W# to 1 above). There is no BYTE count supported, so it does not meet the Intel SMB PIIX4 protocol.

Clock Generator Address (7 bits)	ACK	Byte 0	ACK	Byte 1	ACK
A(6:0) & R/W#					
D3(H)					

C. The data transfer rate supported by this clock generator is 100K bits/sec (standard mode)

D. The input is operating at 3.3V logic levels.

E. The data byte format is 8 bit bytes.

F. To simplify the clock generator I²C interface, the protocol is set to use only block writes from the controller. The bytes must be accessed in sequential order from lowest to highest byte with the ability to stop after any complete byte has been transferred. The Command code and Byte count shown above must be sent, but the data is ignored for those two bytes. The data is loaded until a Stop sequence is issued.

G. In the power down mode (PWR_DWN# Low), the SDATA and SCLK pins are tristated and the internal data latches maintain all prior programming information.

H. At power-on, all registers are set to a default condition. Bytes 0 through 2 default to a 1 (Enabled output state).

Serial Configuration Command Bitmaps

Byte 0: SDRAM Clock Register

BIT	PIN#	PWD	DESCRIPTION
Bit7	18	1	SDRAM7 (Act/Inact)
Bit6	17	1	SDRAM6 (Act/Inact)
Bit5	14	1	SDRAM5 (Act/Inact)
Bit4	13	1	SDRAM4 (Act/Inact)
Bit3	9	1	SDRAM3 (Act/Inact)
Bit2	8	1	SDRAM2 (Act/Inact)
Bit1	5	1	SDRAM1 (Act/Inact)
Bit0	4	1	SDRAM0 (Act/Inact)

Notes: 1 = Enabled; 0 = Disabled, outputs held low

Note: PWD = Power-Up Default

**Functionality**

OE#	SDRAM (0:3)	SDRAM (4:7)	SDRAM (8:11)	SDRAM (12:15)	SDRAM (16:17)
0	Hi-Z	Hi-Z	Hi-Z	Hi-Z	Hi-Z
1	1 X BUF_IN	1 X BUF_IN	1 X BUF_IN	1 X BUF_IN	1 X BUF_IN

Byte 1: SDRAM Clock Register

BIT	PIN#	PWD	DESCRIPTION
Bit 7	45	1	SDRAM15 (Act/Inact)
Bit 6	44	1	SDRAM14 (Act/Inact)
Bit 5	41	1	SDRAM13 (Act/Inact)
Bit 4	40	1	SDRAM12 (Act/Inact)
Bit 3	36	1	SDRAM11 (Act/Inact))
Bit 2	35	1	SDRAM10 (Act/Inact)
Bit 1	32	1	SDRAM9 (Act/Inact)
Bit 0	31	1	SDRAM8 (Act/Inact))

Notes: 1 = Enabled; 0 = Disabled, outputs held low

Note: PWD=Power-Up Default

Byte 2: PCICLK Clock Register

BIT	PIN#	PWD	DESCRIPTION
Bit 7	28	1	SDRAM17 (Act/Inact)
Bit 6	21	1	SDRAM16 (Act/Inact)
Bit 5	-	1	Reserved
Bit 4	-	1	Reserved
Bit 3	-	1	Reserved
Bit 2	-	1	Reserved
Bit 1	-	1	Reserved
Bit 0	-	1	Reserved

Notes: 1 = Enabled; 0 = Disabled, outputs held low

ICS9179B-01 Power Management

The values below are estimates of target specifications.

Condition	Max 3.3V supply consumption Max discrete cap loads VDD = 3.465V All static inputs = VDD or GND
No Clock Mode (BUF_IN - VDD1 or GND) I ² C Circuitry Active	3mA
Active 66MHz (BUF_IN = 66.66MHz)	115mA
Active 100MHz (BUF_IN = 100.00MHz)	180mA



Absolute Maximum Ratings

Supply Voltage	7.0 V
Logic Inputs	GND -0.5 V to V _{DD} +0.5 V
Ambient Operating Temperature	0°C to +70°C
Storage Temperature	-65°C to +150°C

Stresses above those listed under *Absolute Maximum Ratings* may cause permanent damage to the device. These ratings are stress specifications only and functional operation of the device at these or any other conditions above those listed in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect product reliability.

Electrical Characteristics - Input & Supply

T_A = 0 - 70°C; Supply Voltage V_{DD} = 3.3 V +/- 5% (unless otherwise stated)

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
Input High Voltage	V _{IH}		2		V _{DD} +0.3	V
Input Low Voltage	V _{IL}		V _{SS} -0.3		0.8	V
Input High Current	I _{IH}	V _{IN} = V _{DD}			5	uA
Input Low Current	I _{IL}	V _{IN} = 0 V; Inputs with no pull-up resistors	-5			uA
	I _{IL}	V _{IN} = 0 V; Inputs with 100K pull-up resistors	-60	-33		uA
Operating Supply Current	I _{DD1}	C _L = 0 pF; F _{IN} @ 66M		80	120	mA
	I _{DD2}	C _L = 0 pF; F _{IN} @ 100M		120	180	mA
	I _{DD3}	C _L = 30 pF; RS=33Ω; F _{IN} @ 66M		180	260	mA
	I _{DD4}	C _L = 30 pF; RS=33Ω; F _{IN} @ 100M		240	360	mA
	I _{DD5}	Stopped, input at 0 or V _{DD}			500	μA
Input frequency	F _i ¹	V _{DD} = 3.3 V; All Outputs Loaded	10		150	MHz
Input Capacitance	C _{IN} ¹	Logic Inputs			5	pF

¹Guaranteed by design, not 100% tested in production.



ICS9179B-01

Electrical Characteristics - SDRAM

$T_A = 0 - 70^\circ C$; $V_{DD} = V_{DDL} = 3.3 V \pm 5\%$; $C_L = 20 - 30 \text{ pF}$ (unless otherwise stated)

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
Output Impedance	R_{DSP}	$V_O = V_{DD} \cdot 0.5$	10		24	Ω
Output Impedance	R_{DSN}	$V_O = V_{DD} \cdot 0.5$	10		24	Ω
Output High Voltage	V_{OH}	$I_{OH} = -36 \text{ mA}$	2.4	3		V
Output Low Voltage	V_{OL}	$I_{OL} = 23 \text{ mA}$		0.27	0.4	V
Output High Current	I_{OH}	$V_{OH} = 2.0 \text{ V}$		-115	-54	mA
Output Low Current	I_{OL}	$V_{OL} = 0.8 \text{ V}$	40	57		mA
Rise Time ¹	T_r	$V_{OL} = 0.4 \text{ V}, V_{OH} = 2.4 \text{ V}$		0.95	1.33	ns
Fall Time ¹	T_f	$V_{OH} = 2.4 \text{ V}, V_{OL} = 0.4 \text{ V}$		0.95	1.33	ns
Duty Cycle ¹	D_t	$V_T = 1.5 \text{ V}$	45	51	55	%
Skew ¹	T_{sk}	$V_T = 1.5 \text{ V}$		110	250	ps
Propagation ¹	T_{PROP}	$V_T = 1.5 \text{ V}$	1	5	6	ns
	$T_{PROOPEN}$	$V_T = 1.5 \text{ V}$	1		8	ns
	$T_{PROPPDIS}$	$V_T = 1.5 \text{ V}$	1		8	ns

¹Guaranteed by design, not 100% tested in production.

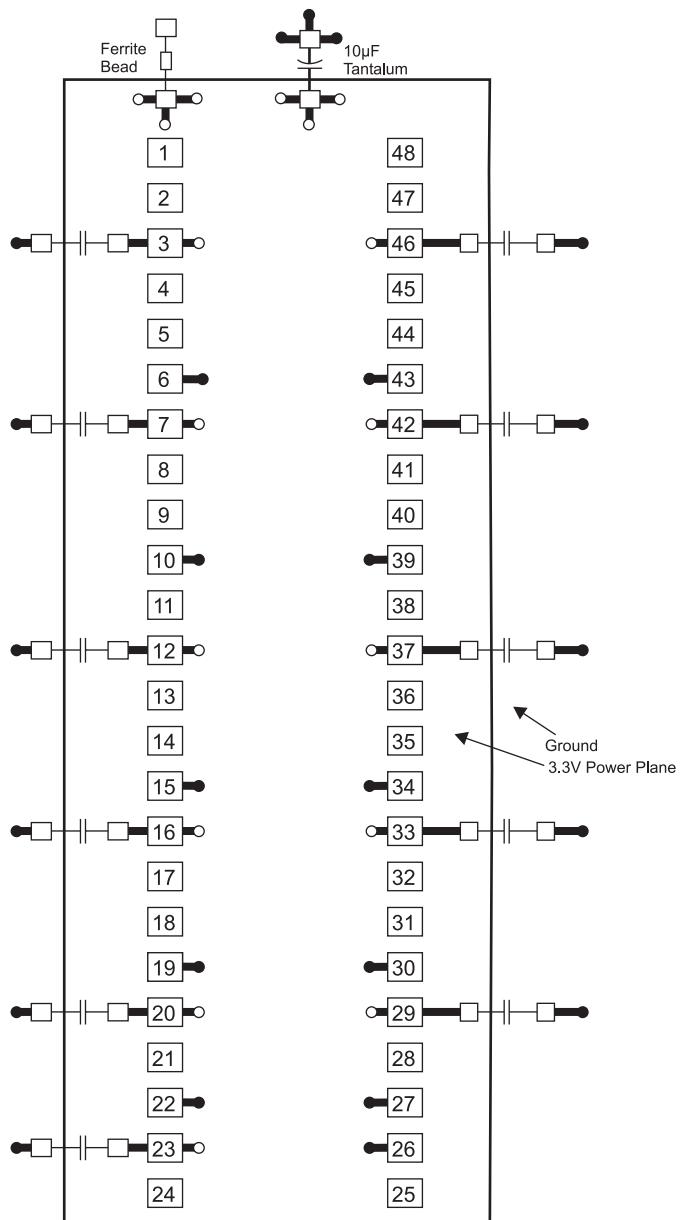


General Layout Precautions:

- 1) Use a ground plane on the top layer of the PCB in all areas not used by traces.
- 2) Make all power traces and vias as wide as possible to lower inductance.

Notes:

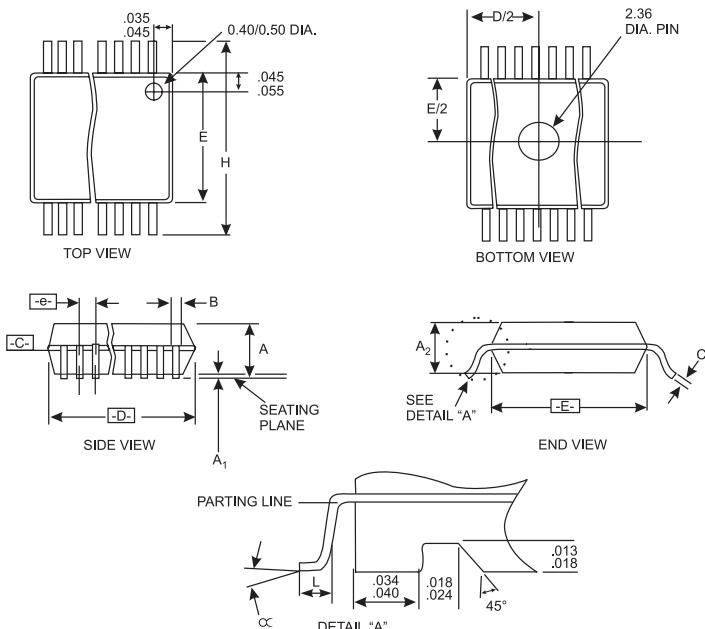
- 1 All clock outputs should have series terminating resistor. Not shown in all places to improve readability of diagram
- 2 Optional EMI capacitor should be used on all CPU, SDRAM, and PCI outputs.



- = Ground Plane Connection
- = Power Plane Connection
- = Solder Pads

Capacitor Values:

All unmarked capacitors are 0.01 μ F ceramic.



SSOP Package

SYMBOL	COMMON DIMENSIONS			VARIATIONS	D			N
	MIN.	NOM.	MAX.		MIN.	NOM.	MAX.	
A	.095	.101	.110	AC	.620	.625	.630	48
A1	.008	.012	.016					
A2	.088	.090	.092					
B	.008	.010	.0135					
C	.005	-	.010					
D	See Variations							
E	.292	.296	.299					
e	0.025 BSC							
H	.400	.406	.410					
h	.010	.013	.016					
L	.024	.032	.040					
N	See Variations							
∞	0°	5°	8°					
X	.085	.093	.100					

Ordering Information

ICS9179BF-01

Example:

ICS XXXX F - PPP

Pattern Number (2 or 3 digit number for parts with ROM code patterns)

Package Type
F=SSOP

Device Type (consists of 3 or 4 digit numbers)

Prefix

ICS, AV = Standard Device